



Z-COAT 401

Wafer Temporary Bonding Adhesive for Application up to 270°C

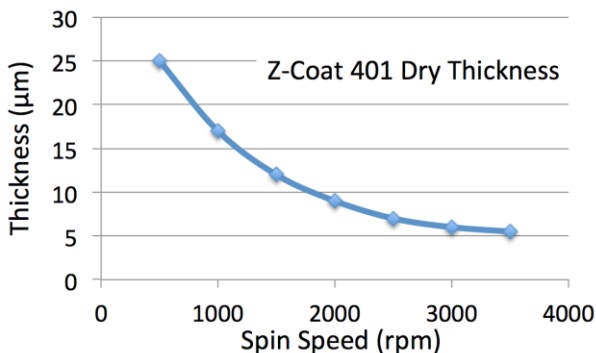
PRODUCT DESCRIPTION

Z-Coat 401 is a thermal plastic transparent adhesive designed for wafer to carrier bonding. Z-Coat 401 resists neutral and acid aqueous solution and compatible with most metals, glass, ceramic and related materials. Debond with room temperature air-jet or high temperature thermal slide.

BASIC MATERIAL PROPERTIES

Z-Coat 401	
Appearance	Clear Liquid
Odor	Slightly
Viscosity	600 ~ 700 cps
Solvent	Yes
Thermal Stability	Up to 270°C
Coating	Spin Coating
Package	Available in 1 kg and 1 gallon bottle
Storage	Room Temperature

SPIN COATING



The recommended Z-Coat 401 thickness for bonding is 17 ~ 20 µm

HARD BAKE

Thickness	Step Hard Bake
5 ~ 12 µm	150 °C for 10 minutes
10 ~ 20 µm	80 °C for 5 minutes + 180 °C for 5 minutes

Recommended bake schedule after spin coating

THERMAL STABILITY:

Weight Loss < 2 % at 250°C for 1 hour

TRANSPARENCY:

Z-Coat 401 is transparent after hard bake to remove solvent.

WAFER BONDING:

Temperature: > 150 °C

Pressure: > 3 PSI

Vacuum: lower than 10⁻³Pa

Time > 2 min at peak temperature

WAFER DEBONDING:

Thermal Slide:

Temperature: > 180 °C

Mechanical:

Air Jetting

Room Temperature

CLEANING

Z-Coat 401 can be easily removed by soaking in Z-clean 820C (aqueous detergent solution), or polar aprotic solvent, followed by di-water rinse. Warm the cleaner to 60~70°C for best cleaning result.

GENERAL INFORMATION

For safe handling information on this product, consult Material Safety Data Sheet (MSDS).

DISCLAIMER

The data contained herein are furnished for information only and are believed to be reliable. It's user's responsibility to determine suitability for user's purpose and to adopt precautions against hazards when handling the product.